

TITLE OF THE INVENTION

New chemical mechanical polishing process for layers of isolating materials based on silicon derivatives or silicon.

TEXT OF THE ABSTRACT

Process for the chemical mechanical polishing of a layer of isolating material based on silicon or a silicon derivative, in which abrasion of the layer of isolating material is carried out by rubbing said layer using a fabric which brings into play an abrasive containing an acid aqueous solution of colloidal silica containing individualized colloidal silica particles, not linked together by siloxane bonds, and water as the suspension medium and new abrasives based on such suspensions.